Thermal transfer compounds

Silicon thermal transfer compound

– thermal transfer compound used to reduce the thermal transmission resistance between semiconductor and heatsink

art. no.	basin	delivery quantity [g]
WLP 004	box	4
WLP 035	box	35
WLP 500	box	500
WLP 300 S	cartridge (310 ml)	300
WLP 500 S	cartridge (310 ml)	500

Silicone-free thermal transfer compound

– thermal transfer compound used to reduce the thermal transmission resistance between semiconductor and heatsink

art. no.	basin	delivery quantity [ml]	delivery quantity [g]
WLPF 05	syringe	2	—
WLPF 10	syringe	5	—
WLPF 20	syringe	10	—
WLPF 50	syringe	20	—
WLPF 300 S	cartridge (310 ml)	—	300

	WLP	**WLPF**
composition	silicone oil, inorganic filling material	silicone free synthetic liquid. Metal oxide filling.
consistance	pastey	
colour	white	white-grey
tightness	1.1 g/cm^3	ca. 2 g/cm^3
thermal conductivity	0.61 W/m·K	>0.7 W/m·K
specific electrical resistance	>10^{12} Ω/cm	
flashpoint	none (DIN 53213)	of the basic oil >280 °C (ISO 2592)
drop point	>260 °C	
thermal resistance	no bleeding at (4 h / 200°C)	<1 % (96 h / 200 °C)
temperature range	-70 °C ... +250 °C	-40 °C ... +150 °C
acid number	< 0.01 mg KOH/g	
solubility in water	insoluble	

Mica wafers → **E 17**
Thermal conductive foil → **E 7 – 10**
Thermal conductive paste → **E 19 – 20**
Thermal conductive glue → **E 21 – 22**
Thermal conductive material → **E 2 – 5**
Insulating caps → **E 49**
Aluminium oxide wafers → **E 15 – 16**
Technical introduction → **A 2 – 7**